

# 225mA, 250V Dual High Speed Switching Diode

#### **FEATURES**

- AEC-Q101 qualified
- Fast switching speed
- Low leakage current
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

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- High-speed switching at high voltage
- High-voltage general-purpose switching

<b>MECHANICAL</b>	<b>DATA</b>
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• Case: SOT-23

- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Weight: 8.00mg (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
lf	225	mA			
V <sub>RRM</sub>	250	V			
I <sub>FSM</sub>	9	Α			
T <sub>J</sub> MAX	150	°C			
V <sub>F</sub> at I <sub>F</sub> =200mA	1.25	V			
Configuration [		die			



PACKAGE: SOT-23	PIN CONFIGURATION	CIRCUIT DIAGRAM
3 4 69 M <sub>2</sub>	3	ANODE  CATHODE  3  ANODE  CATHODE  CATHODE

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Power dissipation <sup>(1)</sup>	PD	350	mW			
Repetitive peak reverse voltage	$V_{RRM}$	250	V			
Forward current	l <sub>F</sub>	225	mA			
Repetitive peak forward current	I <sub>FRM</sub>	625	mA			
	t = 10ms		1.7	Α		
Non-repetitive peak forward surge current	t = 100µs	I <sub>FSM</sub>	3	Α		
	t = 1µs		9	Α		
Junction temperature	TJ	-55 to +150	°C			
Storage temperature	T <sub>STG</sub>	-55 to +150	°C			

## Note:

1. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance <sup>(1)</sup>	Reja	357	°C/W		

#### **Thermal Performance Note:**

1. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>F</b> amoural coals and (1)	I <sub>F</sub> = 100mA		-	-	1.00	V
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 200mA	V <sub>F</sub>		-	1.25	
Reverse breakdown voltage	I <sub>R</sub> = 100μA	$V_{BR}$	250	-	-	V
Develope autromat(2)	V <sub>R</sub> = 200V	_	ı	-	0.1	μΑ
Reverse current <sup>(2)</sup>	V <sub>R</sub> = 200V, T <sub>J</sub> = 150°C	l <sub>R</sub>	ı	-	100	μΑ
Junction capacitance	$f = 1MHz, V_R = 0V$	C		-	5	pF
Reverse recovery time	$I_F = I_R = 30\text{mA},$ $I_{RR} = 3\text{mA}, R_L = 100\Omega$	t <sub>rr</sub>	-	-	50	ns

#### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION						
ORDERING CODE PACKAGE PACKING						
BAV23SH RFG	SOT-23	3,000 / 7" Tape & Reel				



# **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Power Dissipation Curve** 

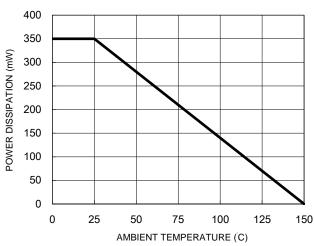


Fig.3 Typical Reverse Characteristics

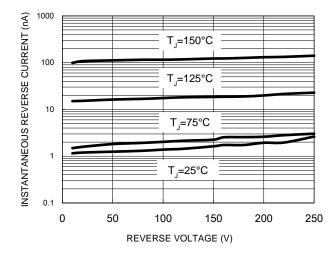


Fig.2 Typical Junction Capacitance

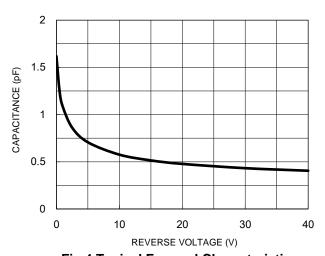
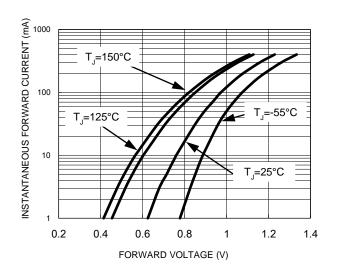


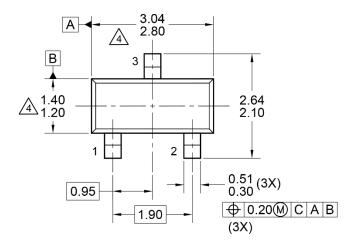
Fig.4 Typical Forward Characteristics

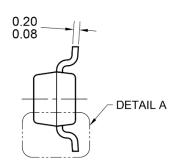


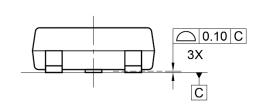


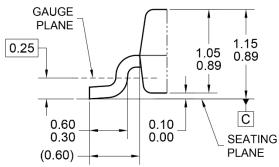
### **PACKAGE OUTLINE DIMENSIONS**

#### **SOT-23**





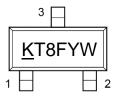




0.85

DETAIL A, ROTATED -90° (SCALE 2:1)

SUGGESTED PAD LAYOUT



MARKING DIAGRAM

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-236, ISSUE H, VARIATION AA.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DWG NO. REF: HQ2SD07-SOT23JEDEC-104 REV B.

<u>K</u>T8 = Device marking F = Factory code

Y = Year code

W = Bi-Week code (A~Z)



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